

Tool ID: 319
Tool Location: 102

Equipment Information Sheet

Veeco Savannah ALD

Manager: Jeremy Clark 607-254-6487
Backup: Philip Schneider 607-254-4931

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Uses highly toxic & reactive / pyrophoric precursors for film deposition. Materials are monitored by TGMCS.

USAGE RESTRICTIONS

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

MATERIALS COMPATIBILITY CATEGORY

Tool Category 4: Glass and Metal Categories

Allowed	Not Allowed
Tool category 1/1E, 2, and 3 materials	
Silicon Based Substrates and Films	No CNF Class A metals
III/V compound Semiconductors	No Exposed CNF Group B metals- <i>metals can be buried/covered with staff approval</i>
Glass Substrates	Cannot be used as an etch stop
PECVD and ALD Films	
Buried Class B Metals with approval	
Organic/Bio Materials prepped w/o Salt Buffers	
Cured organics and baked Photoresist	No High Vapor pressure materials

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No films thicker than 50nm or 500 loops without permission of the tool manager
- All sizes from pieces to 200mm wafers allowed

Last Updated: 05/11/2026